Title (en)
   METHOD FOR JOINING DISPERSION-STRENGTHENED ALLOY

Title (de)
   VERFAHREN ZUR VERBINDUNG EINER DISPERSIONSVERFESTIGTEN LEGIERUNG

Title (fr)
   PROCEDE DESTINE A ASSEMBLER UN ALLIAGE RENFORCE DE DISPERSION

Publication
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Application
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Priority
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Abstract (en)
   [origin: WO2005105362A1] The present invention relates to a method for joining two or more components and/or construction parts, at least one of
   which consists of a dispersion-strengthened alloy having the following composition (in % by weight): C up to 0,08 Si up to 0,7 Cr 10-25 Al 1-10 Mo
   1,5-5 Mn up to 0,4 balance Fe as well as normally occurring impurities by the fact that the cross section in the joint is enlarged by forging before
   joining and where the product manufactured according to the method can be used in high-temperature applications at temperatures above 900 °C.

IPC 8 full level
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   B23K 11/34 (2006.01); B23K 20/24 (2006.01)

IPC 8 main group level
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   C21D 7/13 (2013.01 - EP KR US); **C22C 38/02** (2013.01 - EP KR US); **C22C 38/04** (2013.01 - EP KR US); **C22C 38/06** (2013.01 - EP KR US);
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